ON Semiconductor

Initial Product/Process Change Notification

Document # : IPCN21000X
Issue Date: 6 August 2015

Title of Change:	Product Transfer of Ball Grid Array (BGA) from J-Device Kitakami to J-Device Kitsuki
Proposed first ship date:	18 June 2016
Contact information:	Contact your local ON Semiconductor Sales Office or <Fumio.Baba@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office.
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Affected products will be identified with marking lot number.
Change category:	☐ Wafer Fab Change ☒ Assembly Change ☐ Test Change ☐ Other ______________

Change Sub-Category(s):

☒ Manufacturing Site Change/Addition
☐ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ______________________

Sites Affected:

☐ All site(s) ☐ not applicable ☐ ON Semiconductor site(s) : ☒ External Foundry/Subcon site(s)
J-Devices Corporation

Description and Purpose:

Assembly site of Ball Grid Array (BGA) products will be transferred to J-Device Kitsuki Center from J-Devices Kitakami Center to optimize the production of package deployment among J-Devices Corporation group. The current material used, process flow, process control and product specification such as visual, physical dimension, electrical characteristic will remain the same.

Note: Current test site for the affected products doesn't change.

Qualification Plan:

Estimated date for qualification completion: 19 February 2016

Test:	Conditions:	Interval:
HTOL (High Temperature Operational Life)	TA = 125°C	1008 hrs
HTSL (High Temperature Storage Life)	150°C	1008hrs
THB (High Temperature Bias)	85°C/85% RH	1008 hrs
AC (AutoClave)	121°C/100%RH/15 psig	96 hrs
TC (Temperature Cycling)	-65°C to +150°C	500 cycles
RSH	Resistance to Solder Heat	2 times

List of Affected Standard Parts:

Part Number	Qualification Vehicle
LC823425-13W1-E	LC823425-13W1-E
LC823425-13W1-LR-E	LC823425-13W1-E
LC823425-14S1-E	LC823425-13W1-E

List of Affected Customer Specific Parts:

NOTE: Please be informed that parts impacted by this PDN/PCN are Special/Customer specific parts, thus MPN & CPN info will be available to affected customers only by clicking the "Custom PCN for Selected Company Button" in the Document Analysis page of PCMS/PCN Alert.